

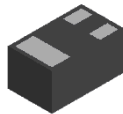
## Features

- $BV_{CEO} > -40V$
- $I_C = -100mA$  High Collector Current
- $P_D = 1000mW$  Power Dissipation
- $0.60mm^2$  Package Footprint, 13 times Smaller than SOT23
- 0.5mm Height Package Minimizing Off-Board Profile
- Complementary NPN Type 2DC4617QLP
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free, "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

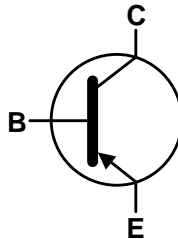
## Mechanical Data

- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound.  
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — NiPdAu
- Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.0008 grams (Approximate)

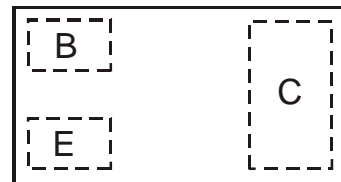
X1-DFN1006-3



Bottom View



Device Symbol

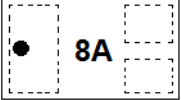
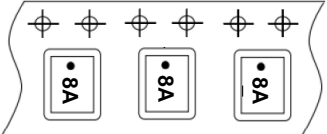
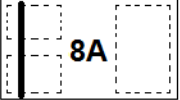
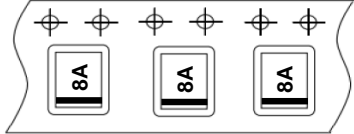
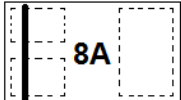
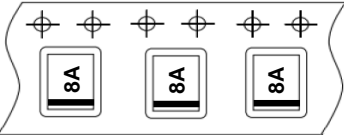

 Top View  
Device Schematic

## Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
2DA1774QLP-7	8A	7	8	3,000
2DA1774QLP-7B	8A	7	8	10,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information

<b>2DA1774QLP-7</b>	 <p>Top View Dot Denotes Collector Side</p> 	<p>From date code 1527 (YYWW), this changes to:</p>  <p>Top View Bar Denotes Base and Emitter Side</p> 
<b>2DA1774QLP-7B</b>	 <p>Top View Bar Denotes Base and Emitter Side</p>  <p>8A = Product Type Marking Code</p>	

**Absolute Maximum Ratings** (@ $T_A = +25^\circ\text{C}$  unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-50	V
Collector-Emitter Voltage	$V_{CEO}$	-40	V
Emitter-Base Voltage	$V_{EBO}$	-5.0	V
Collector Current	$I_C$	-100	mA
Peak Collector Current	$I_{CM}$	-200	mA

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation	$P_D$	400	mW
		1,000	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	310	$^\circ\text{C/W}$
		120	
Thermal Resistance, Junction to Lead	$R_{\theta JL}$	120	$^\circ\text{C/W}$
Operating and Storage and Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**ESD Ratings** (Note 8)

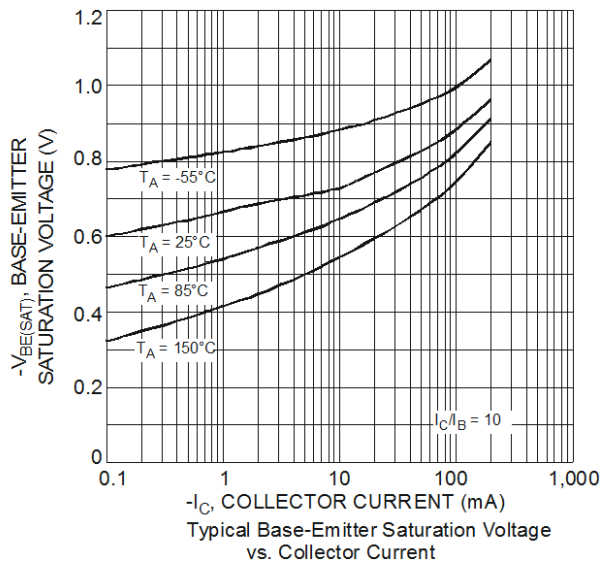
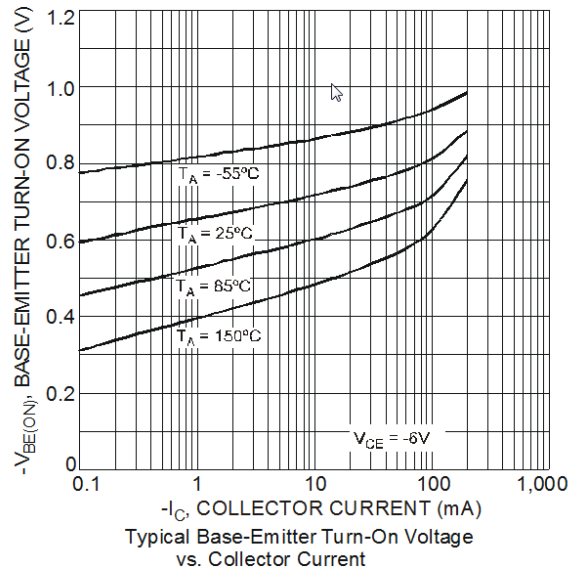
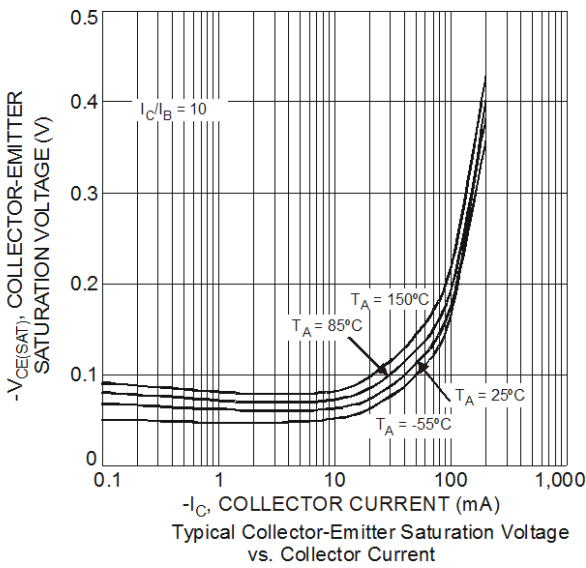
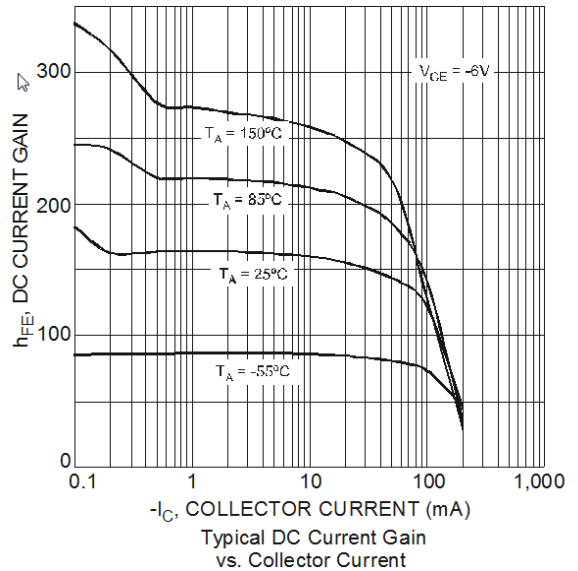
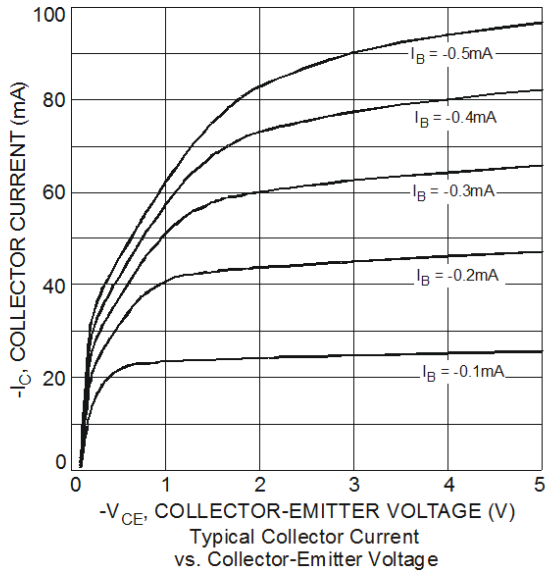
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	200	V	B

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$  unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 9)</b>					
Collector-Base Breakdown Voltage	$BV_{CBO}$	-50	—	V	$I_C = -50\mu\text{A}, I_E = 0$
Collector-Emitter Breakdown Voltage	$BV_{CEO}$	-40	—	V	$I_C = -1\text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	-5.0	—	V	$I_E = -50\mu\text{A}, I_C = 0$
Collector Cutoff Current	$I_{CBO}$	—	-100 -5	nA $\mu\text{A}$	$V_{CB} = -30\text{V}$ $V_{CB} = -30\text{V}, T_A = +150^\circ\text{C}$
Emitter Cutoff Current	$I_{EBO}$	—	-100	nA	$V_{EB} = -4.0\text{V}$
<b>ON CHARACTERISTICS (Note 9)</b>					
DC Current Gain	$h_{FE}$	120	270	—	$V_{CE} = -6.0\text{V}, I_C = -1.0\text{mA}$
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	-0.2	V	$I_C = -50\text{mA}, I_B = -5.0\text{mA}$
<b>SMALL SIGNAL CHARACTERISTICS</b>					
Output Capacitance	$C_{obo}$	—	5.0	pF	$V_{CB} = -12\text{V}, f = 1.0\text{MHz}, I_E = 0$
Current Gain-Bandwidth Product	$f_T$	100	—	MHz	$V_{CE} = -12\text{V}, I_C = -2.0\text{mA}, f = 100\text{MHz}$

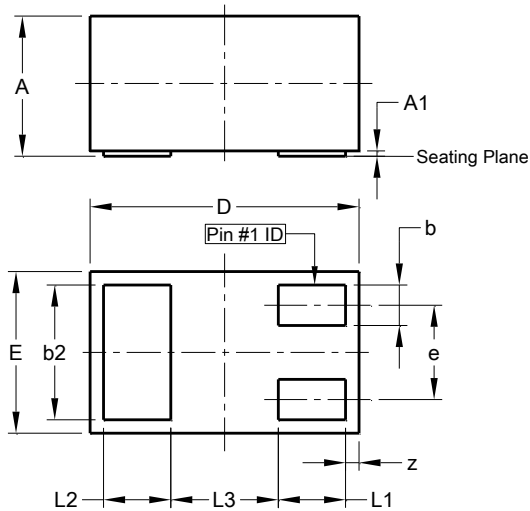
- Notes:
- For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
  - Same as Note 5, except the exposed collector pad is mounted on 25mm x 25mm 2oz copper.
  - Thermal resistance from junction to solder-point (on the exposed collector pad).
  - Refer to JEDEC specification JESD22-A114 and JESD22-A115.
  - Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$ .

**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified)



## Package Outline Dimensions

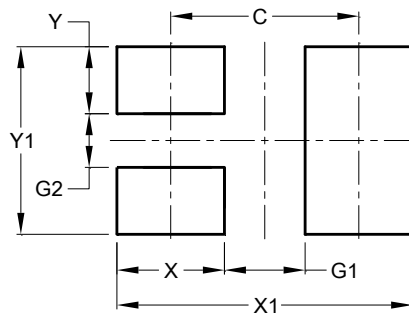
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.00	0.05	0.03
b	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	-	-	0.40
z	0.02	0.08	0.05
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.70
G1	0.30
G2	0.20
X	0.40
X1	1.10
Y	0.25
Y1	0.70

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